

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	707	257/100.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 12:50
L2	2137	257/99.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 13:15
L3	1826	2 not 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 12:51
L4	1021	(led or (light adj emitter) or illuminator) and (heat adj sink) and (bond or (bonding adj pads)) and (epoxy or encapsulant or resin)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 12:51
L5	1789	3 not L4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 12:52
L6	846	257/88.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 13:16
L7	832	6 not 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 13:16
L8	681	7 not 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 13:16

L9	666	8 not 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 13:16
S6	1	("5479029").PN.	USPAT	OR	OFF	2004/11/16 16:16
S7	449	(led or (light adj emitter)) and (heat adj sink) and (bond or (bonding adj pads)) and (epoxy or encapsulant or resin) and (wires or wire)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 00:24
S8	317	S7 and (gold or silver or au or ag)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 16:19
S9	212	S8 and (nickel or titanium or ti or ni)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 17:52
S10	1	"5917234".PN.	USPAT; USOCR	OR	OFF	2004/11/16 17:46
S11	1	"5893724".PN.	USPAT; USOCR	OR	OFF	2004/11/16 17:47
S12	1	"5773895".PN.	USPAT; USOCR	OR	OFF	2004/11/16 17:47
S13	1	"5767446".PN.	USPAT; USOCR	OR	OFF	2004/11/16 17:47
S14	741	257/88.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 18:12
S15	1112	257/79.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 18:12
S16	564	257/81.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 18:13

S17	335	257/95.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 18:13
S18	1877	257/99.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 18:13
S19	576	257/100.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 18:13
S20	4328	S14 S15 S16 S17 S18 S19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 18:13
S21	262	S20 and (heat adj sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 09:18
S22	768831	"15" and (resin or epoxy or encapsulant)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 20:02
S23	1112	257/79.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 20:02
S24	294	S23 and (resin or epoxy or encapsulant)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 20:03

S25	741	257/88.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 20:03
S26	564	257/81.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 20:03
S27	335	257/95.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 20:03
S28	1877	257/99.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 20:03
S29	576	257/100.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 12:43
S30	4328	S25 S23 S26 S27 S28 S29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 20:03
S31	1517	S30 and (resin or epoxy or encapsulant)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 20:03
S32	262	S30 and (heat adj sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 20:03

S33	1399	S31 not S32	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/16 20:04
S34	7487	(led or (light adj (emitter or emitting))) and (heat adj sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/18 15:55
S35	339	S34 and ((bond or bonding) adj pads)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/18 15:56
S36	132	S35 and (semiconductor near5 substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/18 19:51
S37	1538	362/800.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/18 19:52
S38	803	362/240.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/18 19:52
S39	1822	362/294.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/18 19:52
S40	752	362/373.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/18 19:52

S41	4250	S37 S38 S39 S40	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/18 19:52
S42	73	S41 and ((semiconductor or si or silicon) near6 substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 09:23
S43	964	372/36.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/19 12:50
S44	964	372/36.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 09:26
S45	1018	(led or (light adj emitter) or illuminator) and (heat adj sink) and (bond or (bonding adj pads)) and (epoxy or encapsulant or resin)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 00:27
S46	770	S45 and (wire or wires)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/11 00:26
S47	846	257/88.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 09:18
S48	1379	257/79.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 09:18

S49	665	257/81.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 09:18
S50	367	257/95.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 09:18
S51	2137	257/99.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 09:18
S52	707	257/100.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 09:18
S53	5016	S47 S48 S49 S50 S51 S52	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 09:18
S54	336	S53 and (heat adj sink)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 09:18
S55	1695	362/800.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 09:23
S56	855	362/240.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 09:23

S57	1910	362/294.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 09:23
S58	813	362/373.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 09:23
S59	4525	S55 S56 S57 S58	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 09:23
S60	86	S59 and ((semiconductor or si or silicon) near6 substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 09:24
S61	1066	372/36.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/11 09:26